

SUPPLEMENT NO. 7 TO PART 748 - AUTHORIZATION VALIDATED END-USER (VEU): LIST OF VALIDATED END-USERS, RESPECTIVE ITEMS ELIGIBLE FOR EXPORT, REEXPORT AND TRANSFER, AND ELIGIBLE DESTINATIONS

Country	Validated End-User	Eligible Items (By ECCN)	Eligible Destination	Federal Register Citation
Nothing in this Supplement shall be deemed to supersede other provisions in the EAR, including but not limited to § 748.15(c).				
China (People’s Republic of)	Advanced Micro Devices China, Inc.	3D002, 3D003, 3E001 (limited to “technology” for items classified under 3C002 and 3C004 and “technology” for use during the International Technology Roadmap for Semiconductors (ITRS) process for items classified under ECCNs 3B001 and 3B002), 3E002 (limited to “technology” for use during the ITRS process for items classified under ECCNs 3B001 and 3B002), 3E003.e (limited to the “development” and “production” of integrated circuits for commercial applications), 4D001, and 4E001 (limited to the “development” of products under ECCN 4A003).	<p>Advanced Micro Devices (Shanghai) Co., Ltd. Buildings 33 (Unit 1), 46, 47, 48 & 49, River Front Harbor, Zhangjiang Hi-Tech Park, No. 1387 Zhangdong Rd., Pudong, Shanghai, China 201203.</p> <p>AMD Technology Development (Beijing) Co., Ltd. North and South Buildings RaycomInfotech, Park Tower C, No. 2 Science Institute South Rd., Zhong Guan Cun, Haidian District, Beijing, China 100190.</p> <p>AMD Products (China) Co. Ltd. North and South Buildings RaycomInfotech Park Tower C, No. 2 Science Institute South Rd., Zhong Guan Cun, Haidian District, Beijing, China 100190.</p>	75 FR 25763, 5/10/10. 76 FR 2802, 1/18/11. 78 FR 3319, 1/16/13. 81 FR 40783, 6/23/16.

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	Advanced Micro-Fabrication Equipment, Inc., China	2B230, 3B001.a.2, and 3B001.e (items classified under ECCNs 3B001.a.2, and 3B001.e are limited to components and accessories).	Advanced Micro-Fabrication Equipment, Inc., China 188 Taihua Road Jinqiao Export Processing Zone (South Area) Pudong, Shanghai 201201, China.	78 FR 41291, 7/10/13. 80 FR 65931, 10/28/15.
	Applied Materials (China), Inc.	<i>These Items Authorized for those Applied Materials Destinations Identified by one asterisk (*):</i> 2B006.b, 2B230, 2B350.g.3, 2B350.i, 3B001.a, 3B001.b, 3B001.e, 3B001.f, 3C001, 3C002, 3D002 (limited to “software” specially designed for the “use” of stored program controlled items classified under ECCN 3B001).	*Applied Materials South East Asia Pte. Ltd. Shanghai Depot c/o Shanghai Applied Materials Technical Service Center No. 2667 Zuchongzhi Road, Shanghai, China 201203. *Applied Materials South East Asia Pte. Ltd. Beijing Depot c/o Beijing Applied Materials Technical Service Center No. 1 North Di Sheng Street, BDA Beijing, China 100176. *Applied Materials South East Asia Pte. Ltd. Wuxi Depot c/o Sinotrans Jiangsu Fuchang Logistics Co., Ltd. 1 Xi Qin Road, Wuxi Export Processing Zone Wuxi, Jiangsu, China 214028.	72 FR 59164, 10/19/07. 74 FR 19382, 4/29/09. 75 FR 27185, 5/14/10. 77 FR 10953, 2/24/12. 80 FR 65931, 10/28/15.

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			<p>*Applied Materials South East Asia Pte. Ltd. Wuhan Depot c/o Wuhan Optics Valley Import & Export Co., Ltd. No. 101 Guanggu Road East Lake High-Tec Development Zone Wuhan, Hubei, China 430074.</p> <p>*Applied Materials (China), Inc. Shanghai Depot No. 2667, Zuchongzhi Road Shanghai, China 201203.</p> <p>*Applied Materials (China), Inc. Beijing Depot No. 1 North Di Sheng Street, BDA Beijing, China 100176.</p>	

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		<p><i>These Items Authorized for the Applied Materials Destination Identified by two asterisks (**):</i> 2B006.b, 2B230, 2B350.g.3, 2B350.i, 3B001.a, 3B001.b, 3B001.e, 3B001.f, 3C001, 3C002, 3D002 (limited to “software” specially designed for the “use” of stored program controlled items classified under ECCN 3B001), and 3E001 (limited to “technology” according to the General Technology Note for the “development” or “production” of items controlled by ECCN 3B001).</p>	<p>**Applied Materials (Xi’an) Ltd. No. 28 Xin Xi Ave., Xi’an High Tech Park Export Processing Zone Xi’an, Shaanxi, China 710075.</p>	
		<p><i>This item is authorized for the Applied Materials Destination Identified by three asterisks (***):</i> 3E001 (limited to “technology” according to the General Technology Note for the “development” or “production” of items controlled by ECCN 3B001).</p>	<p>*** Applied Materials (China), Inc. – Headquarters 1388 Zhangdong Road, Bldg. 22 Zhangjiang Hi-Tech Park, Pudong Shanghai, 201203, China.</p>	

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	Boeing Tianjin Composites Co. Ltd.	1B001.f, 1D001 (limited to “software” specially designed or modified for the “use” of equipment controlled by 1B001.f), 2B001.b.2 (limited to machine tools with accuracies no better than (<i>i.e.</i> , not less than) 13 microns), 2D001 (limited to “software,” other than that controlled by 2D002, specially designed or modified for the “use” of equipment controlled by 2B001.b.2), and 2D002 (limited to “software” for electronic devices, even when residing in an electronic device or system, enabling such devices or systems to function as a “numerical control” unit, capable of coordinating simultaneously more than 4 axes for “contouring control” controlled by 2B001.b.2).	Boeing Tianjin Composites Co. Ltd., 4566 Heibei Road, Marine Hi-Tech Development Area, Tanggu District, Tianjin, China 300451	72 FR 59164, 10/19/07. 74 FR 19382, 4/29/09. 77FR 10953, 2/24/12. 77 FR 40258, 7/9/12. 81 FR 61104, 9/6/16.
	CSMC Technologies Corporation	1C350.c.4, 1C350.c.12, 2B230.a, 2B230.b, 2B350.f, 2B350.g, 2B350.h, 3B001.e, 3B001.h (except for multilayer masks with a phase shift layer designed to produce “space qualified” semiconductor devices), 3C002.a, and 3C004.	CSMC Technologies Fab 1 Co., Ltd., 14 Liangxi Road, Wuxi, Jiangsu 214061, China CSMC Technologies Fab 2 Co., Ltd., 8 Xinzhou Rd., Wuxi National New Hi-Tech Industrial Development Zone, Wuxi, Jiangsu 214028, China	76 FR 2802, 1/18/11. 76 FR 37634, 6/28/11. 77 FR 10953, 2/24/12. 78 FR 23472, 4/19/13. 78 FR 32981, 6/3/13.

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	Intel Semiconductor (Dalian) Ltd.	<i>These items authorized for the Intel destination identified by one asterisk (*):</i> 1A004, 1C006.d, 2A226, 2B006.b, 2B230, 2B231, 2B350, 3A233.a, 3B001 (except for multilayer masks with a phase shift layer designed to produce “space qualified” semiconductor devices), 3C002, 3E002 (excluding “development” and “production” technology specific to digital signal processors and digital array processors and further limited to “technology” based on the international technology roadmap for semiconductors (ITRS)), and 4E001 (limited to “technology” for computer products or components not exceeding an adjusted peak performance (APP) level of 12.0 weighted teraflops).	*Intel Semiconductor (Dalian) Ltd. No. 109 Huai He Road East Dalian Economic and Technology Development Area Dalian, Liao Ning Province, 116600 China	78 FR 54752, 9/6/13. 81 FR 85145, 11/25/16.

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		<p><i>These items authorized for the Intel destination identified by two asterisks (**):</i> 1A004, 1C006.d, 2A226, 2B006.b, 2B230, 2B231, 2B350, 3A233.a, 3B001 (except for multilayer masks with a phase shift layer designed to produce “space qualified” semiconductor devices), and 3C002.</p>	<p>** Intel Semiconductor (Dalian) Ltd. c/o Dalian Kintetsu Logistics Co., Ltd Dayaowan Bonded Port No. 6 Road W4 Unit A1 Dalian Economic and Technology Development Area Dalian, Liao Ning Province, 116601 China</p>	
	Lam Research Service Co., Ltd.	<p><i>These Items Authorized for those Lam’s Destinations Identified by a single asterisk (*):</i> 2B230, 2B350.c, 2B350.d, 2B350.g, 2B350.h, 2B350.i, and 3B001.e (limited to installation, warranty maintenance/repair, or maintenance/repair service of semiconductor manufacturing equipment manufactured by Lam, and items classified under ECCN 3B001.e are limited to specially designed components and accessories), 3D001 (limited to “software” (excluding source code) specially designed for the “development” or “production” of</p>	<p>* Lam Research International Sarl (Lam Beijing Warehouse), c/o Beijing Lam Electronics Tech Center 1 Building, No. 28, Jinghai Second Road, BDA, Beijing, China 100176.</p> <p>* Lam Research International Sarl (Lam Beijing Warehouse), c/o Beijing STE International Logistics Co., Ltd., Building 3, No. 9 Ke Chuang Er Street Beijing Economic & Technological Development Area, Beijing, China 100176.</p>	<p>75 FR 62462, 10/12/10. 77 FR 10953, 2/24/12. 78 FR 3319, 1/16/13. 78 FR 54752, 9/6/13. 79 FR 71014, 12/1/14. 82 FR 48925, 10/23/17.</p>

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		equipment controlled by ECCN 3B001.e)), 3D002 (limited to “software” (excluding source code) specially designed for the “use” of equipment controlled by ECCN 3B001.e)), and 3E001 (limited to “development” “technology” according to the General Technology Note of a type of equipment classified under ECCN 3B001.e).	<p>* Lam Research International Sarl (Lam Beijing Warehouse) c/o China International Electronic Service Company 1 Building, No. 28, Jinghai Second Road, BDA Beijing, China 100176</p> <p>* Lam Research International Sarl (Lam Beijing Warehouse) c/o HMG Hi-Tech Logistics (Beijing) Co., Ltd., Building 3, No. 9 Ke Chuang Er Street Beijing Economic & Technological Development Area, Beijing, China 100176.</p> <p>* Lam Research International Sarl (Lam Dalian Warehouse) c/o Liaoning JD Logistics International Co., Ltd., Dalian Bonded Logistics Port, W5-B8, No. 6, Road #3, Dalian, China 116600.</p>	

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			<p>* Lam Research International Sarl (Lam Dalian Warehouse) c/o Liaoning JD Logistics International Co., Ltd., Dalian Bonded Logistics Zone No. 1 Public Warehouse Dalian, China 116600.</p> <p>* Lam Research International Sarl (Lam Shanghai Warehouse) c/o HMG Supply Chain (Shanghai) Co., Ltd., No. 633, Shangfeng Road, Pudong New District, Shanghai, China 201201.</p> <p>* Lam Research International Sarl (Lam Shanghai Warehouse), c/o Regal Harmony Logistics Co., Ltd., No.799, Yihua Road, Pudong New District, Shanghai, China 201299.</p> <p>* Lam Research International Sarl (Lam Shanghai Warehouse Operator), c/o Shanghai Well-Win Logistics Co., Ltd., No. 2667 Zuchongzhi Road, Pudong New District, Shanghai, China.</p>	

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			<p>* Lam Research International Sarl (Lam Shanghai Warehouse; WGQ Bonded Warehouse) c/o HMG Supply Chain (Shanghai) Co., Ltd., No. 55, Fei La Road, Waigaoqiao Free Trade Zone Pudong New Area, Shanghai, China 200131.</p> <p>* Lam Research International Sarl (Lam Wuhan Warehouse), c/o Wuhan HMG Logistics Co., Ltd., Factory C101/201, 1-2F Building 1, Central China Normal University Park Road, Wuhan, China 430223.</p> <p>* Lam Research International Sarl (Lam Wuxi Warehouse), c/o HMG WHL Logistics (Wuxi) Co., Ltd., Plot J3-4, No. 5 Gaolang East Road, CBZ, New District Wuxi Wuxi, China 214208.</p>	

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			<p>* Lam Research International Sarl (Lam Xiamen Warehouse), c/o VR Int'l Logistics (Xiamen) Co., Ltd., C3 Area No. 3 Warehouse, No. 1007 West Fangshan Road, Bonded Logistics Center (Type B) Xiang'an District, Xiamen, China 361101.</p> <p>* Lam Research International Sarl (Lam Xi'an Warehouse), c/o VR International Logistics (Xi'an) Co., Ltd., No. 28 Information Road, EPZ B Zone, Xi'an New District, Xi'an, China 710119.</p> <p>* Lam Research International Sarl (Wuxi EPZ Bonded Warehouse), c/o HMG WHL Logistics (Wuxi) Co., Ltd., 1st Floor, Area 4, No. 1, Plot J3, No. 5 Gaolang East Road, Export Processing Zone Wuxi, Jiangsu, China 214028.</p>	

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		<p><i>These Items Authorized for those Lam's Destinations Identified by double asterisks (**):</i> 2B230, 2B350.c, 2B350.d, 2B350.g, 2B350.h, 2B350.i, and 3B001.e (limited to installation, warranty maintenance/repair, or maintenance/repair service of semiconductor manufacturing equipment manufactured by Lam, and items classified under ECCN 3B001.e are limited to specially designed components and accessories), 3D001 (limited to “software” (excluding source code) specially designed for the “development” or “production” of equipment controlled by ECCN 3B001.e)), 3D002 (limited to “software” (excluding source code) specially designed for the “use” of equipment controlled by ECCN 3B001.e)), and 3E001 (limited to “development” “technology” or “production” “technology” according to the General Technology Note of a type to support integration, assembly (mounting), inspection, testing, and</p>	<p>** Lam Research Service Co., Ltd. (Shanghai), 1st Floor, Area C, Hua Hong Science & Technology Park, 177 Bi Bo Road, Zhangjiang Hi-Tech Park, Pudong New District, Shanghai, China 201203.</p> <p>** Lam Research Service Co., Ltd. (Xiamen), Room 705A, Qiangye Building, Xiang'an Industrial Park, Xiamen Torch Hi-tech Zone, Xiamen, China 361115.</p> <p>**Lam Research Service Co., Ltd. (Beijing Branch), 6th Floor, Building 52, No.2, Jingyuan North Street, Beijing Economic & Technological Development Area, Beijing, China 100176.</p> <p>** Lam Research Service Co., Ltd. (Dalian Branch), Units 01, 02, 13, 10th Floor, Jinma International Building, No. 1 Yongde Street, Dalian, China 116620</p>	

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		quality assurance of equipment classified under ECCN 3B001.e)).	<p>** Lam Research Service Co., Ltd. (Lam Dalian Representative Office), c/o Intel Semiconductor (Dalian) Ltd., No. 109 Huaihe Road East, Dalian Economic & Technical Development Area, Dalian, China 116600.</p> <p>** Lam Research Service Co., Ltd. (Wuhan Representative Office), Room 302, Guanggu Software Park Building E4, No. 1 Guanshan Road, Wuhan, Hubei Province, China 430074.</p> <p>** Lam Research Service Co., Ltd. (Wuxi Branch), Room 302, Building 6, Singapore International Park, No. 89 Xing Chuang Si Road, Wuxi New District, Wuxi, Jiangsu, China 214028</p> <p>** Lam Research Service (Shanghai) Co., Ltd. (Xi'an Branch), Room 602, Building G, Wangzuo Xiandai City, 35 Tangyan Road, Gaoxin District Xi'an, China 710065.</p>	

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	Samsung China Semiconductor Co. Ltd.	1C350.c.4, 1C350.d.14, 2B006.a, 2B006.b.1.d, 2B230, 2B350.d.2, 2B350.g.3, 2B350.i.3, 3A233, 3B001.a.1, 3B001.b, 3B001.e, 3B001.f, 3B001.h, 3C002, 3C004, 3D002, and 3E001 (limited to “technology” for items classified under 3C002 and 3C004 and “technology” for use consistent with the International Technology Roadmap for Semiconductors process for items classified under ECCNs 3B001 and 3B002).	Samsung China Semiconductor Co., Ltd., No.1999, North Xiaohe Road, Xi’an, China 710119	78 FR 41291, 7/10/13. 78 FR 69535, 11/20/13. 79 FR 30713, 5/29/14. 80 FR 11863, 3/5/15.
	Shanghai Huahong Grace Semiconductor Manufacturing Corporation	1C350.c.4, 1C350.d.14, 2B230, 2B350.d.2, 2B350.g.3, 2B350.i.4, 3B001.a.1, 3B001.b, 3B001.e, 3B001.f, 3B001.h, 3C002, 3C004, 5B002, and 5E002 (controlled by ECCNs 5A002, 5A004, or 5A992 that have been successfully reviewed under the encryption review process specified in Sections 740.17(b)(2) or 740.17(b)(3) of the EAR).	Shanghai Huahong Grace Semiconductor Manufacturing Corporation – HFab 2, 668 Guoshoujing Road, Zhangjiang Hi-Tech Park, Shanghai 201203 China Shanghai Huahong Grace Semiconductor Manufacturing Corporation – HFab 1, 1188 Chuanqiao Road, Pudong, Shanghai 201206 China Shanghai Huahong Grace Semiconductor Manufacturing Corporation – GFab1, 1399 Zuchongzhi Road, Zhangjiang Hi- Tech Park, Shanghai 201203 China	78 FR 32981, 6/3/13.

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	SK hynix Semiconductor (China) Ltd.	3B001.a, 3B001.b, 3B001.e, and 3B001.f.	SK hynix Semiconductor (China) Ltd. Lot K7, Wuxi High-tech Zone Comprehensive Bonded Zone Wuxi New District, Jiangsu Province, China 214028.	75 FR 62462, 10/12/10. 77 FR 40258, 7/9/12. 78 FR 3319, 1/16/13. 78 FR 69535, 11/20/13
	SK hynix Semiconductor (Wuxi) Ltd.	3B001.a, 3B001.b, 3B001.e, and 3B001.f.	SK hynix Semiconductor (Wuxi) Ltd., Lot K7-1, Wuxi High-tech Zone Comprehensive Bonded Zone Wuxi New District, Jiangsu Province, China 214028.	75 FR 62462, 10/12/10. 77 FR 40258, 7/9/12. 78 FR 3319, 1/16/13. 78 FR 69535, 11/20/13
India	GE India Industrial Pvt Ltd.	1C002.a.1, 1C002.a.2, 1C002.b.1.a, 1C002.b.1.b, 1E001, 2E003.f, 9E003.a.1, 9E003.a.2, 9E003.a.4, 9E003.a.5, 9E003.a.6, 9E003.a.8, and 9E003.c.	<p>GE India Technology Centre Private Limited (GEITC) No. 122, EPIP, Phase II Hoodi Village, Whitefield Road Bangalore 560066, Karnataka, India.</p> <p>Bangalore Engineering Center (BEC) c/o GE India Technology Centre Private Limited (GEITC) No. 122, EPIP, Phase II Hoodi Village, Whitefield Road Bangalore 560066, Karnataka, India.</p>	74 FR 31620, 7/2/09. 74 FR 68147, 12/23/09. 77 FR 10953, 2/24/12.